

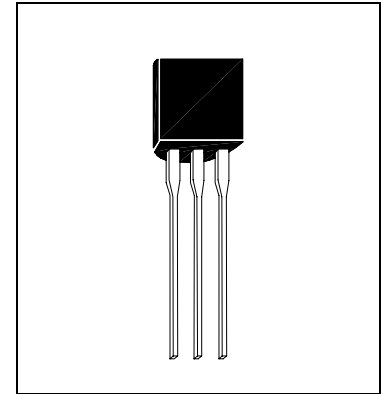


HMPS751

PNP SILICON TRANSISTOR

Description

Amplifier Transistor



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCBO Collector to Base Voltage -80 V
 VCEO Collector to Emitter Voltage -60 V
 VEBO Emitter to Base Voltage -5 V
 IC Collector Current -2 A

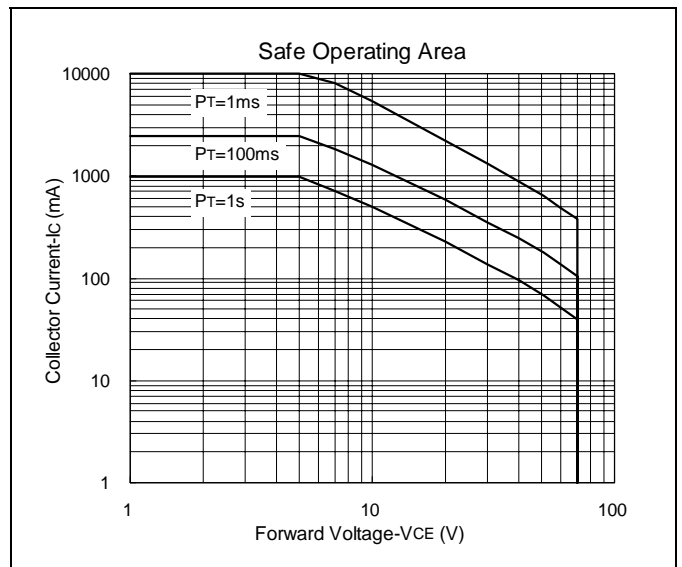
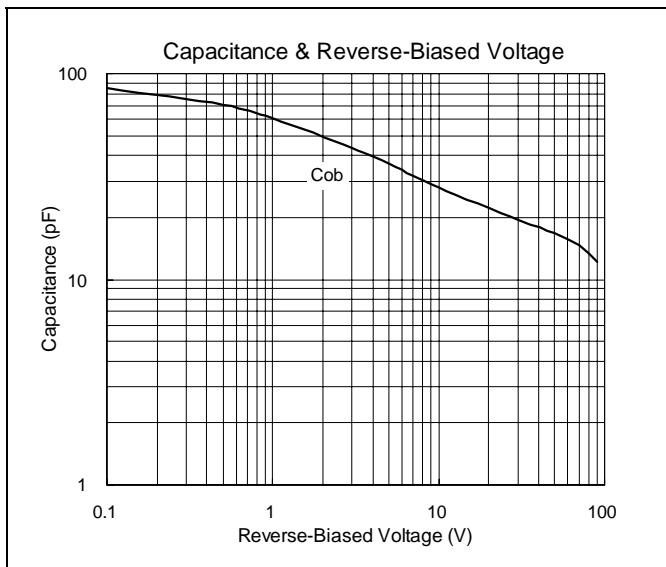
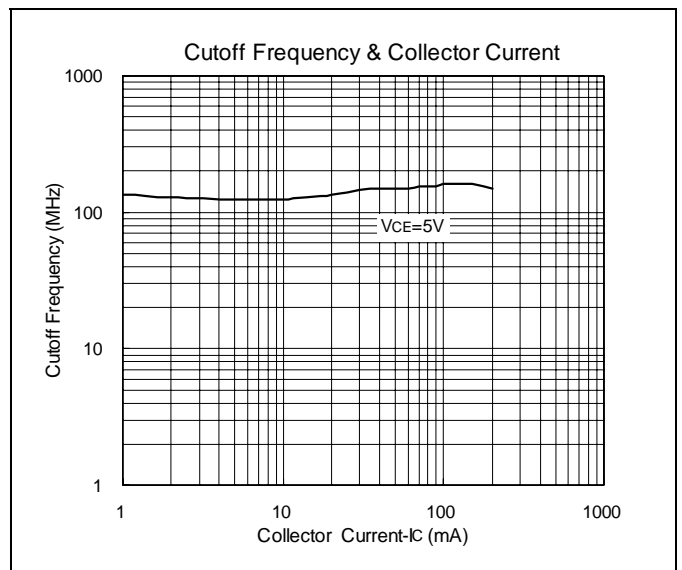
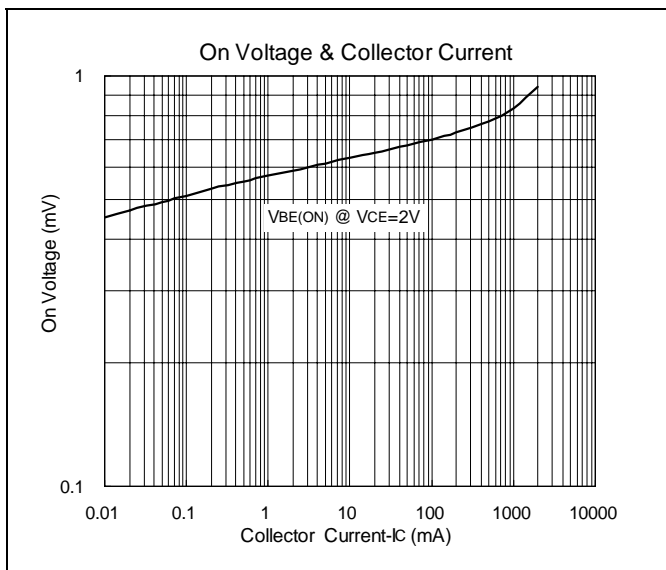
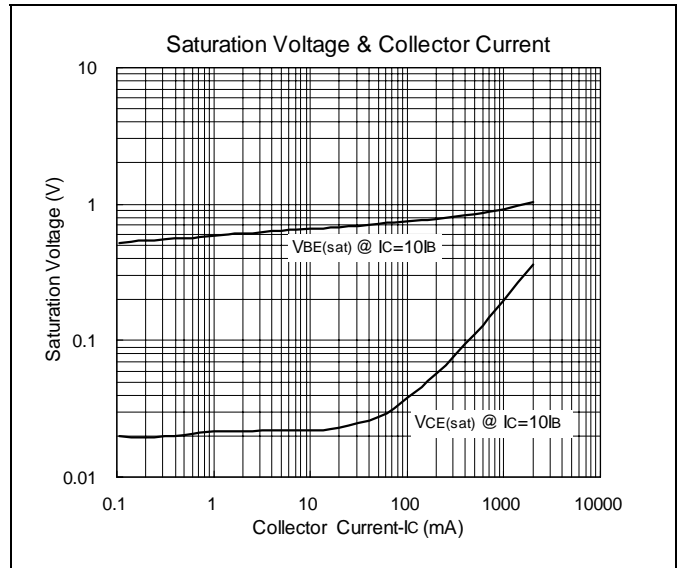
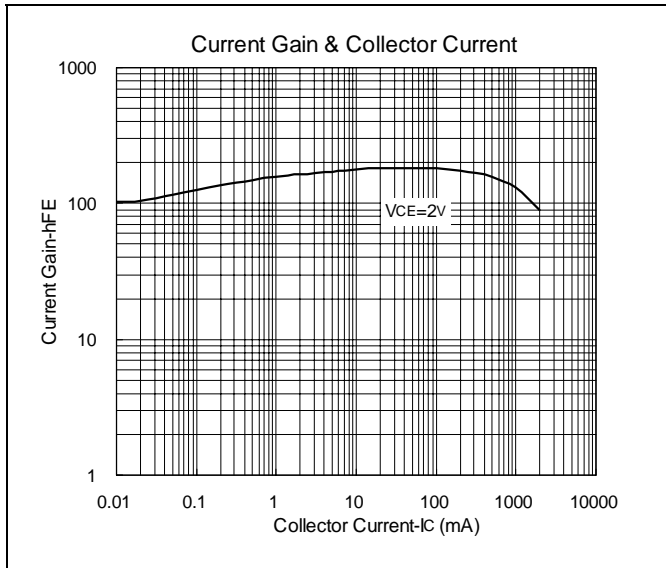
Characteristics (Ta=25°C)

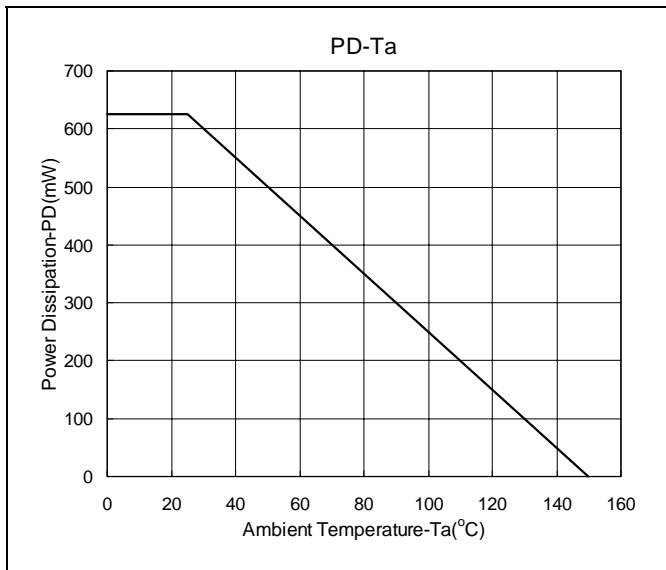
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-80	-	-	V	IC=-100uA, IE=0
BVCEO	-60	-	-	V	IC=-10mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IE=0
ICBO	-	-	-0.1	uA	VCB=-80V, IE=0
IEBO	-	-	-0.1	uA	VEB=-4V, IC=0
*VCE(sat)1	-	-	-0.5	V	IC=-2A, IB=-200mA
*VCE(sat)2	-	-	-0.3	V	IC=-1A, IB=-100mA
*VBE(sat)	-	-	-1.2	V	IC=-1A, IB=-100mA
VBE(on)	-	-	-1	V	IC=-1A, VCE=-2V
*hFE1	75	-	-		IC=-50mA, VCE=-2V
*hFE2	75	-	-		IC=-500mA, VCE=-2V
*hFE3	75	-	-		IC=-1A, VCE=-2
*hFE4	40	-	-		IC=-2A, VCE=-2V
fT	75	-	-	MHz	VCE=-5V, IC=-50mA, f=100MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



Characteristics Curve







TO-92 Dimension

3-Lead TO-92 Plastic Package
 HSMC Package Code : A

Marking :

HSMC Logo → □ □ □ □ ← Product Series
 Part Number → □ □ □ □ □ □
 Date Code → □ □ □ □ □ □ ← Rank
 Laser Mark

HSMC Logo
 Product Series
 Part Number → □ □ □ □ □ □
 Ink Mark

Style : Pin 1. Emitter 2. Base 3. Collector

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

Head Office And Factory :

- **Head Office** (Hi-Sincerity Microelectronics Corp.) : 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
 Tel : 886-2-25212056 Fax : 886-2-25632712, 25368454
- **Factory 1** : No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel : 886-3-5983621~5 Fax : 886-3-5982931
- **Factory 2** : No. 17-1, Ta-Tung Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel : 886-3-5977061 Fax : 886-3-5979220